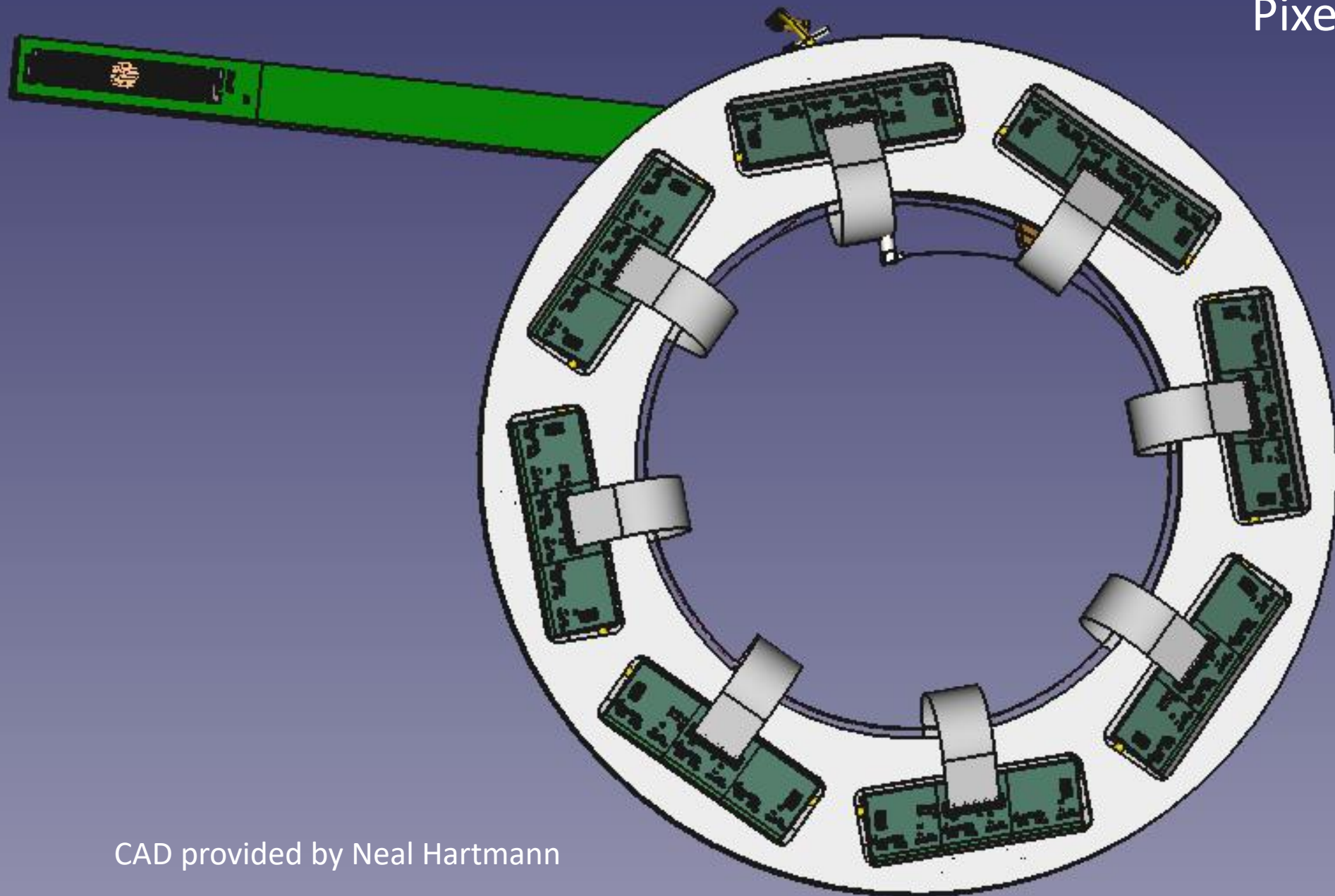
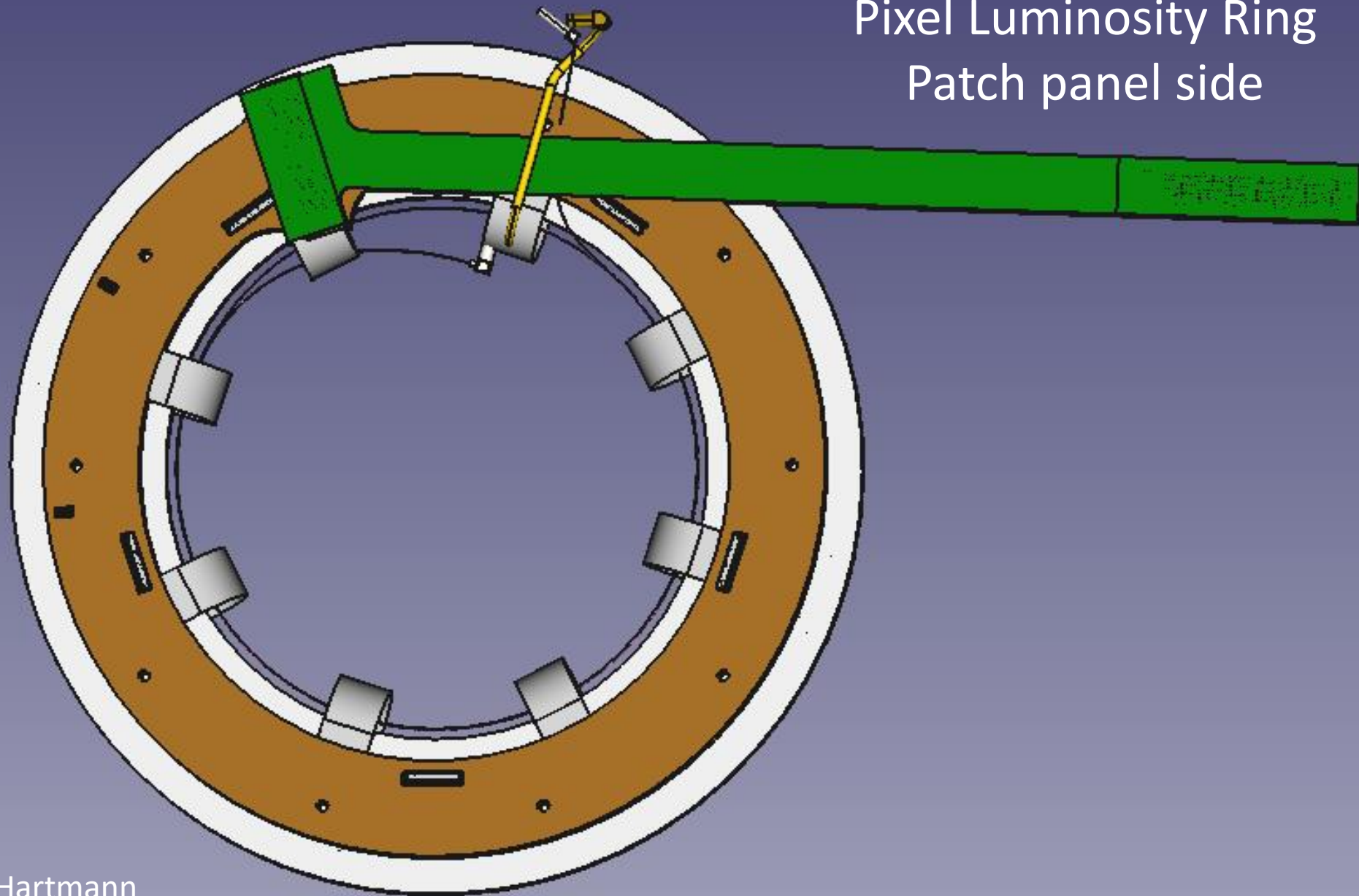


Pixel Luminosity Ring Module side



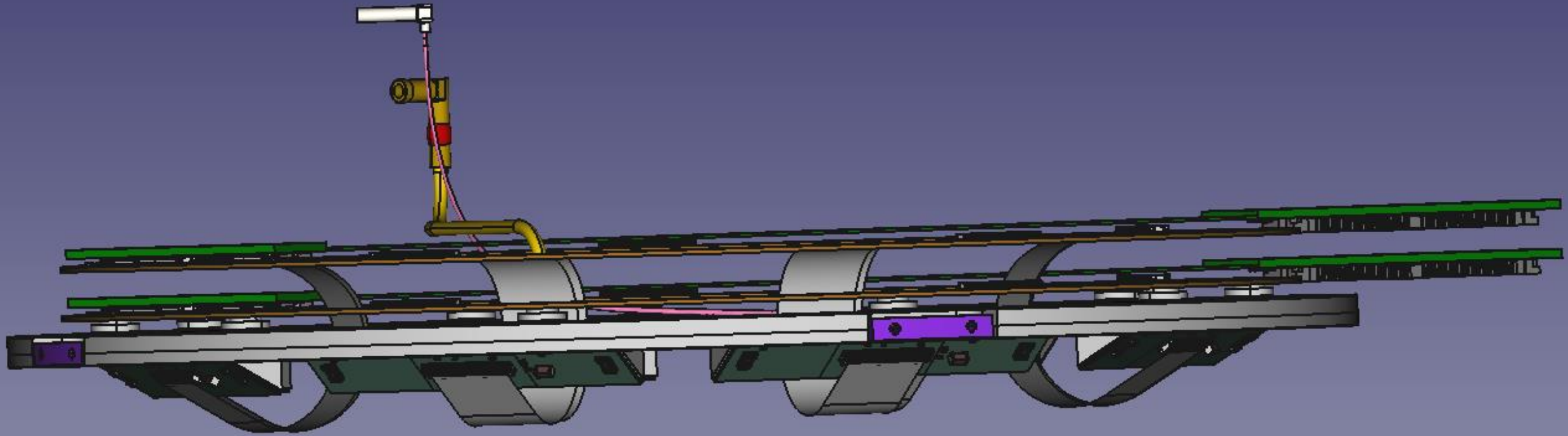
CAD provided by Neal Hartmann

Pixel Luminosity Ring
Patch panel side



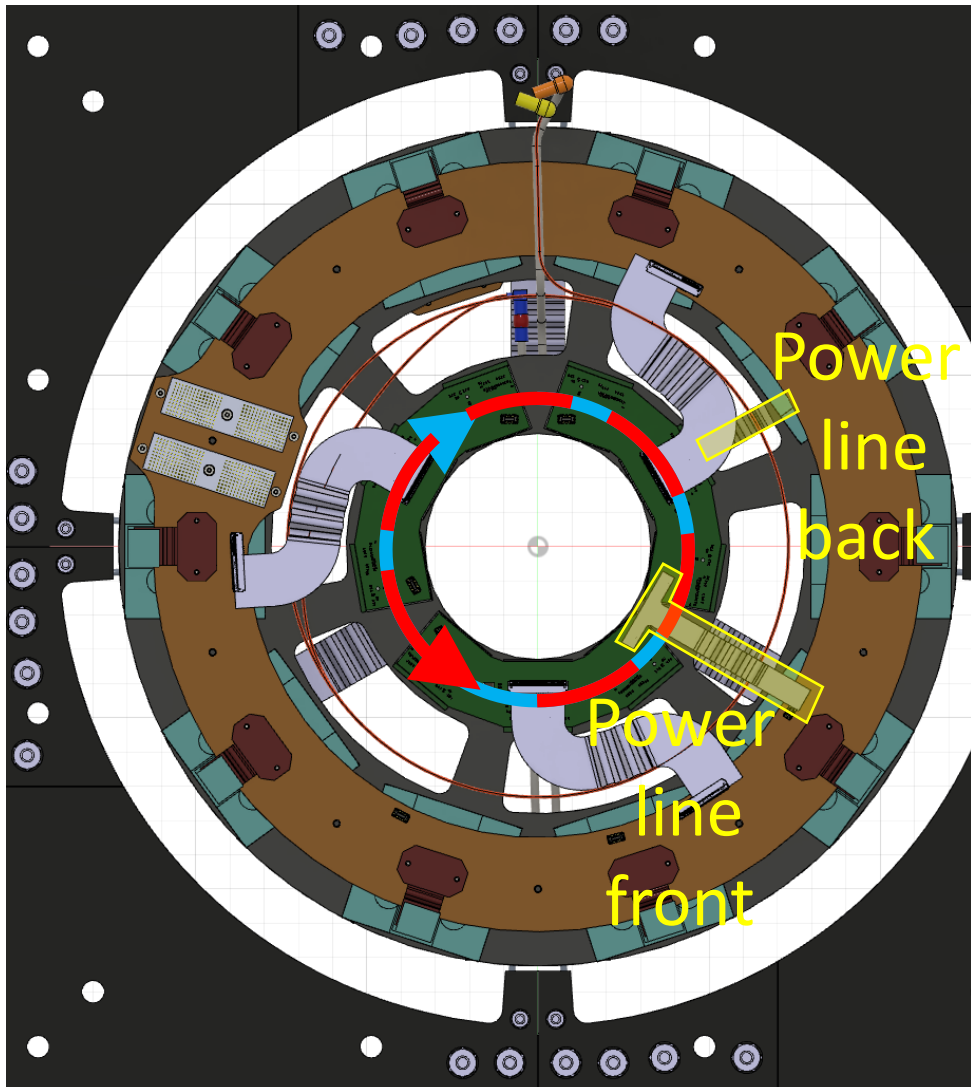
CAD provided by Neal Hartmann

Pixel Luminosity Ring
Side view : 2 patch panels



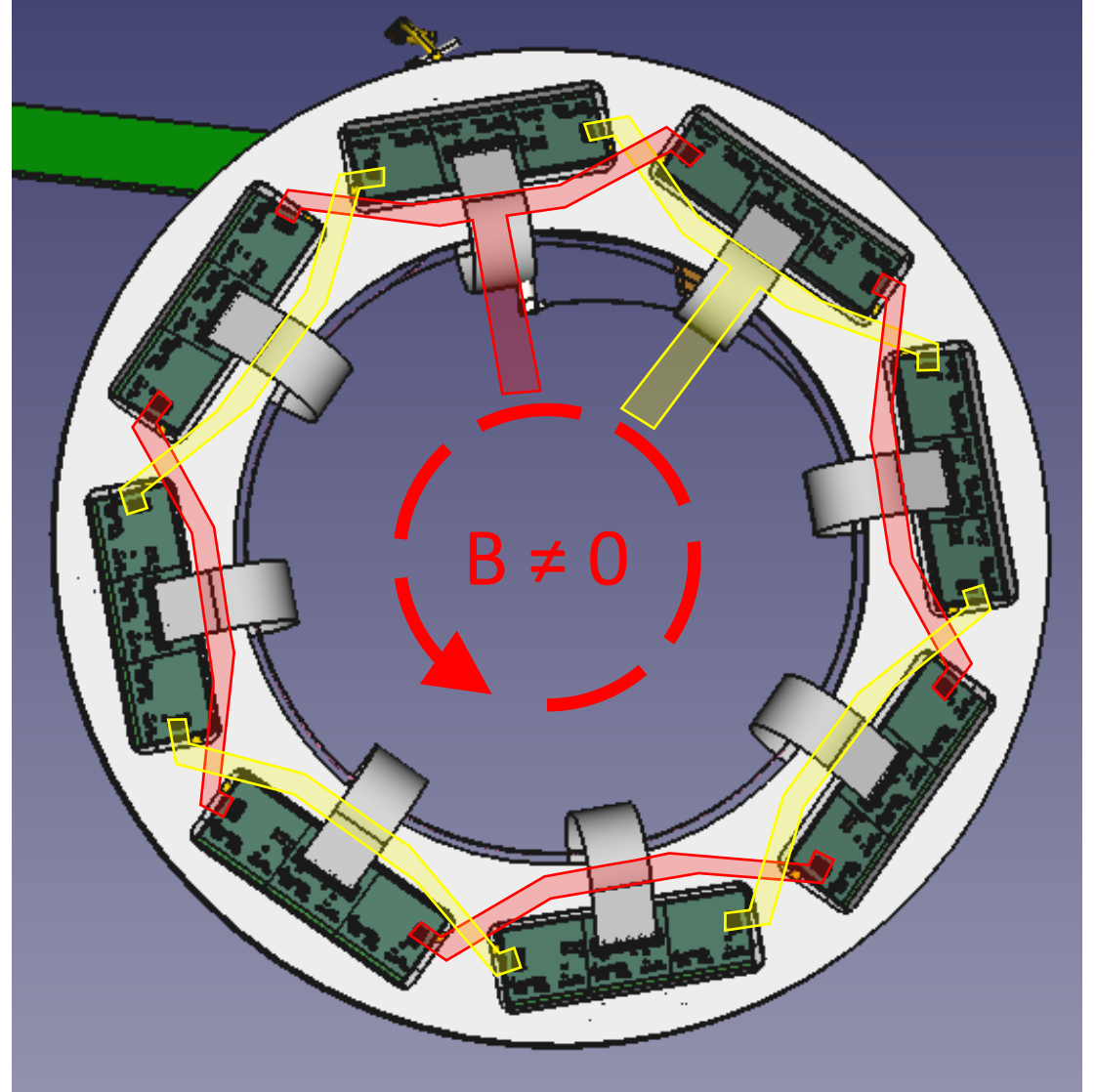
CAD provided by Neal Hartmann

Power line design B field cancellation

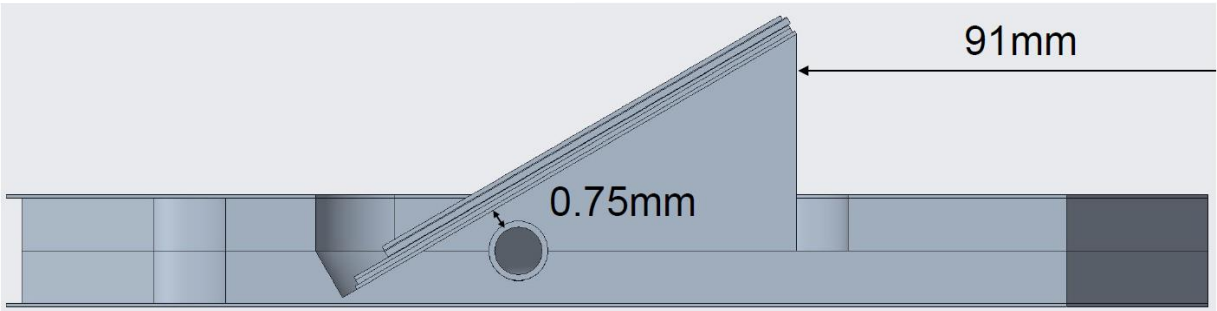
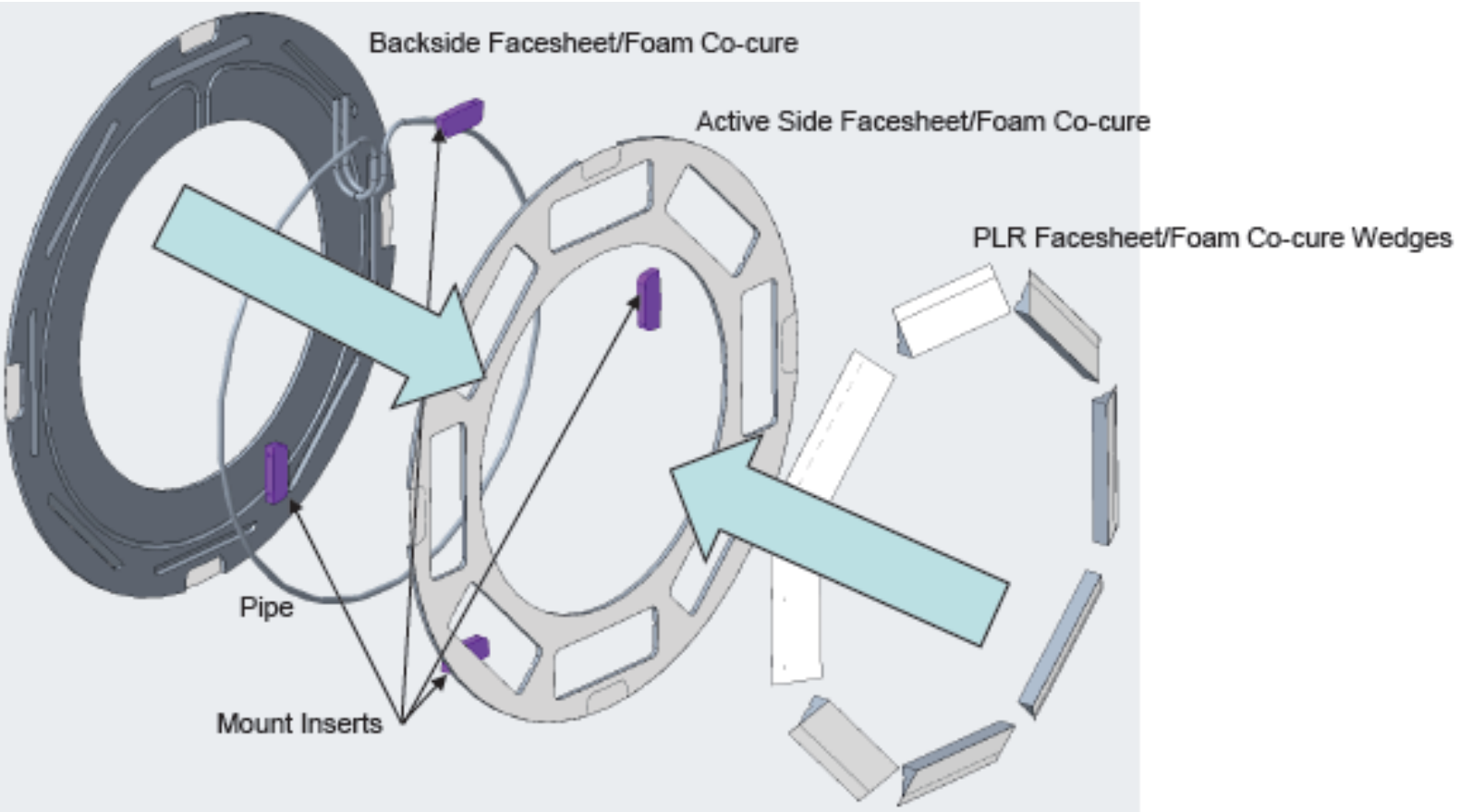


The power line has to be designed to cancel the B field.

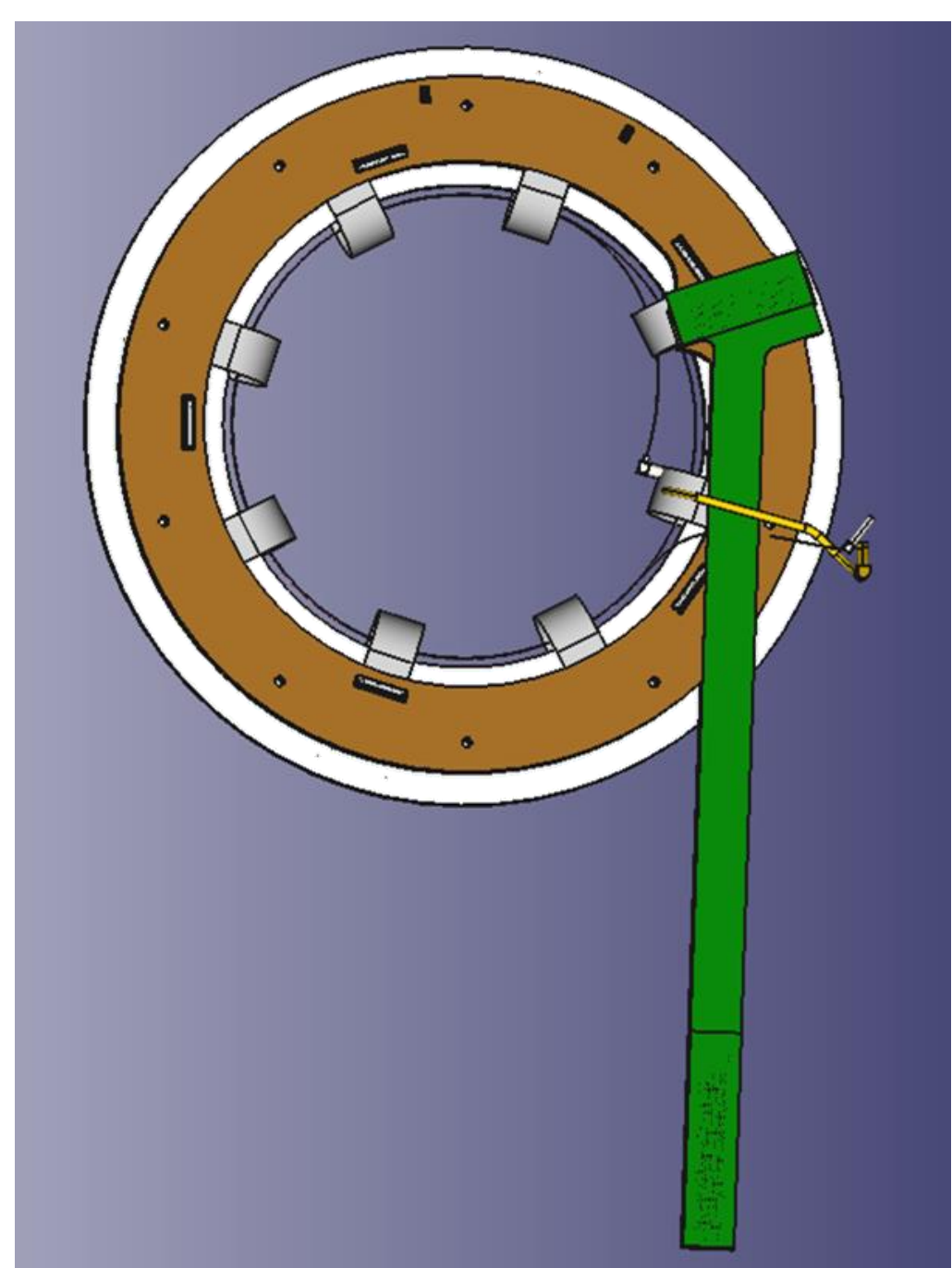
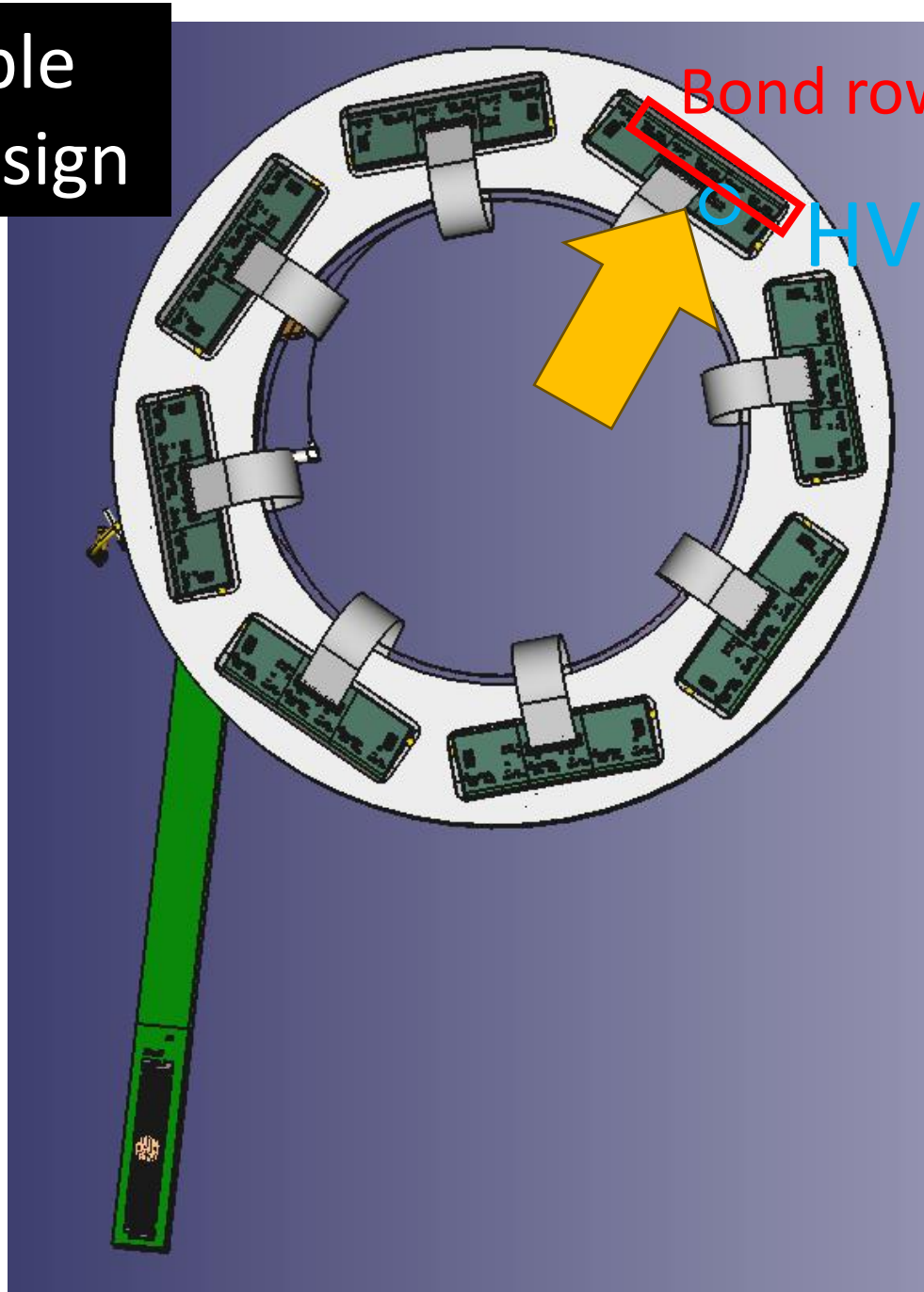
Question: is it possible to power 8 modules with a single power line



Reproduced from
Pixel Luminosity Ring
Project Description



Incompatible
flex cable design

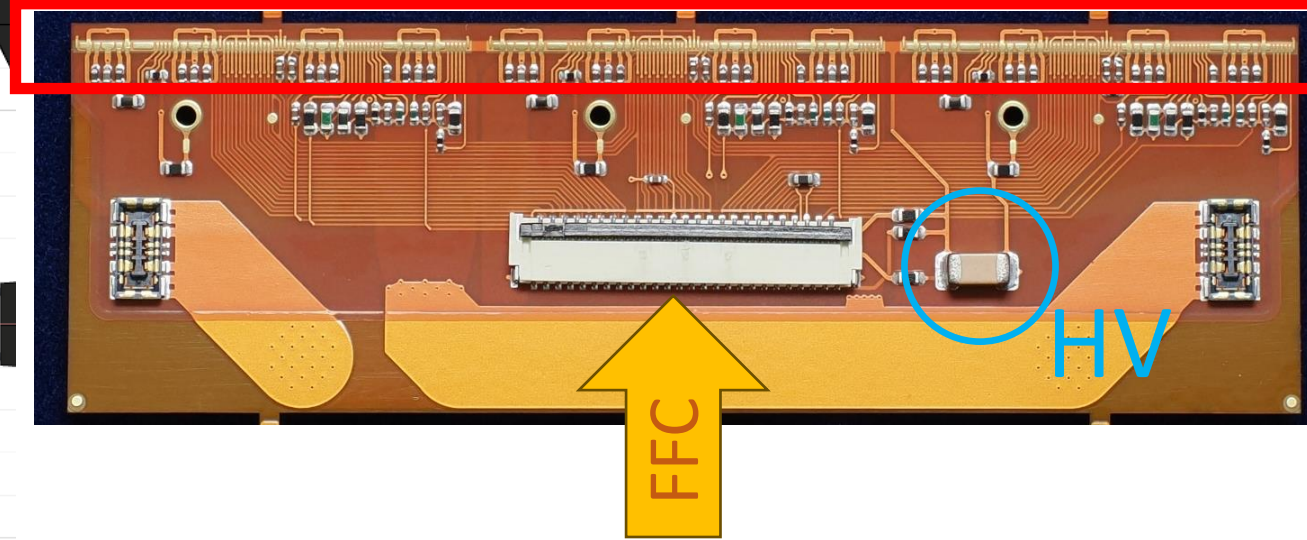


Idea: adapt the ring 0 design



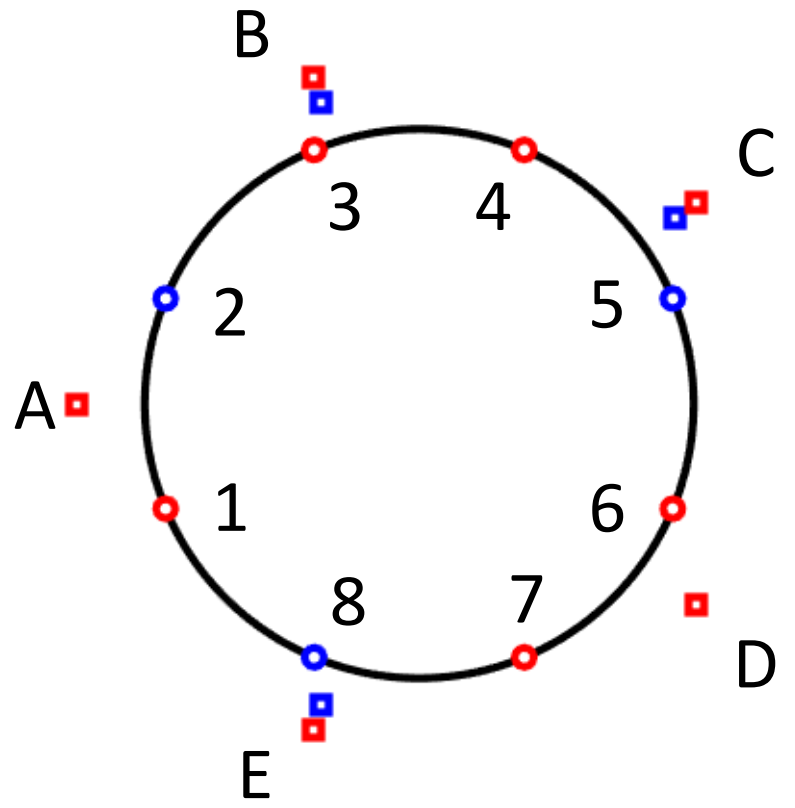
With a linear triplet

Bond row



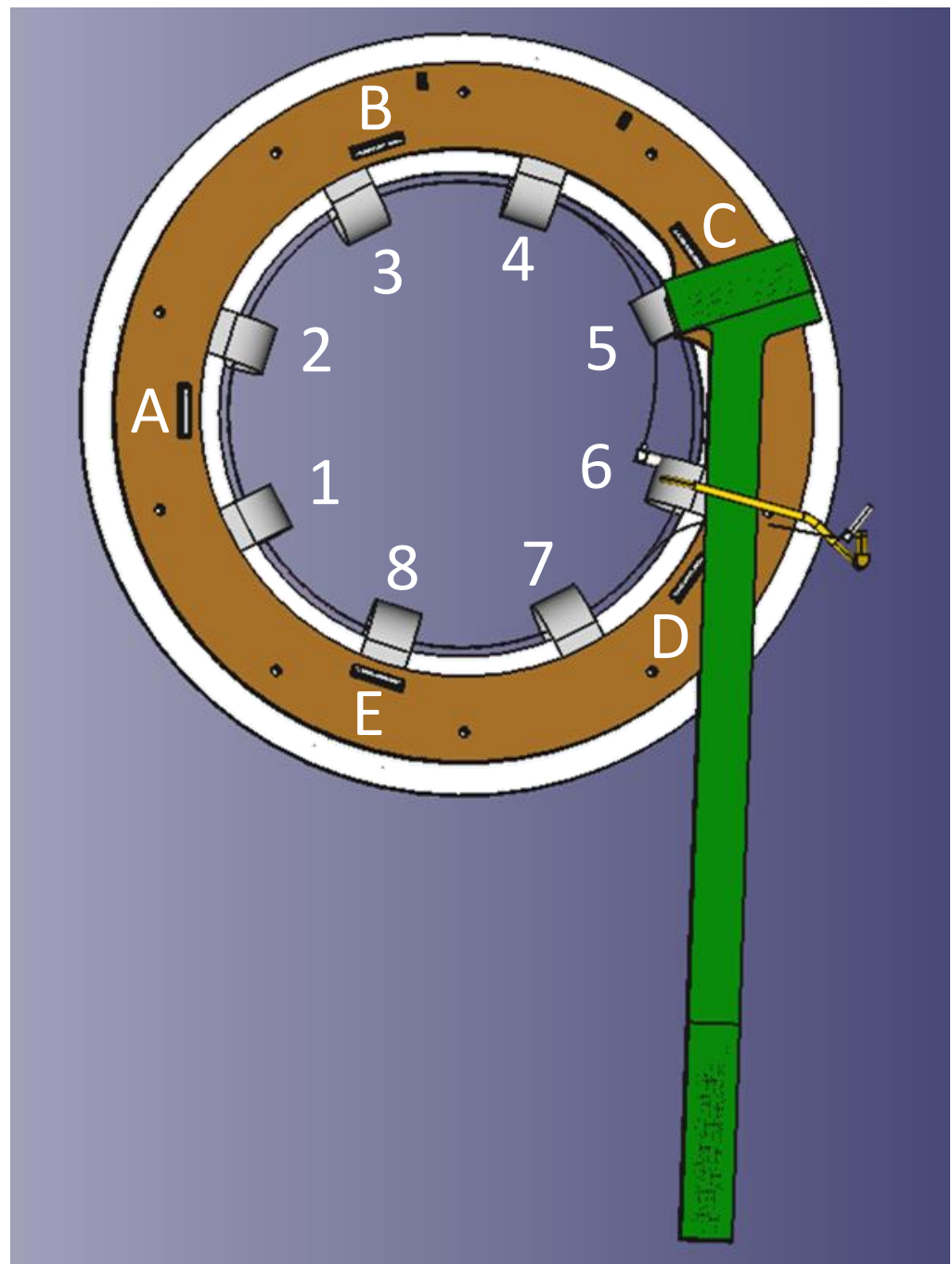
Incompatible topology/geometry!

flex cable connection to patch panel



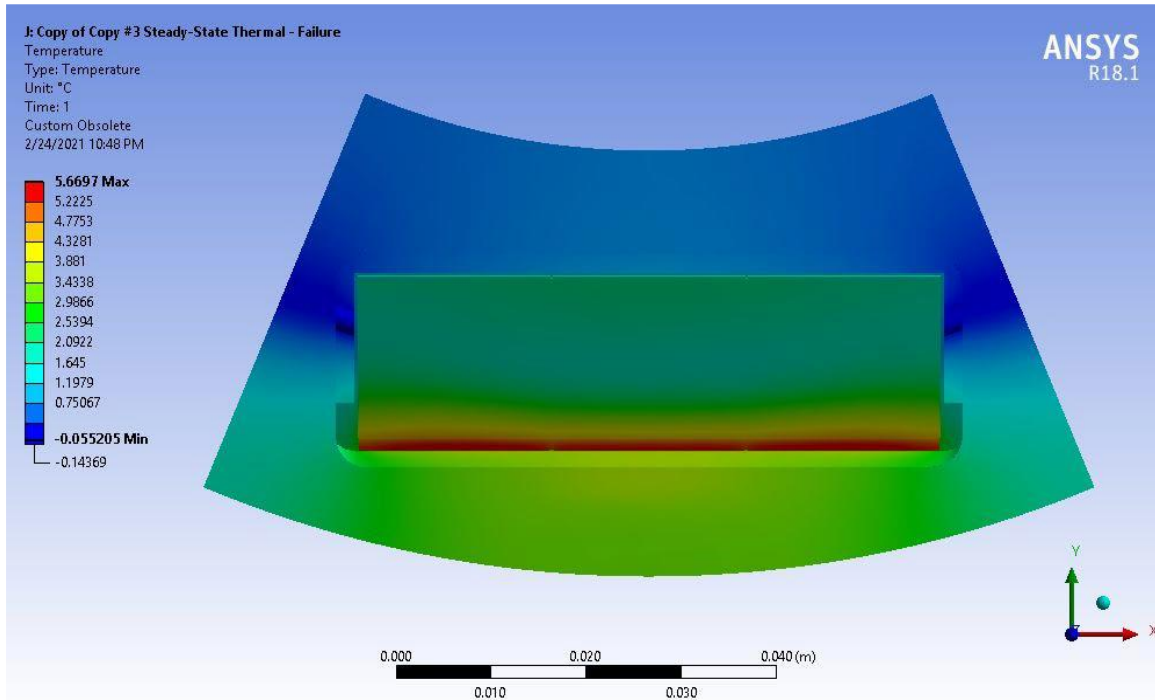
Module	1	2	3	4	5	6	7	8
Connector	A - l	B - u	B - l	C - l	C - u	D - l	E - l	E - u

Probably 7 to E2 and 8 to E1 is a more practical option.
 Connecting two flex cables on top of each other could be challenging.

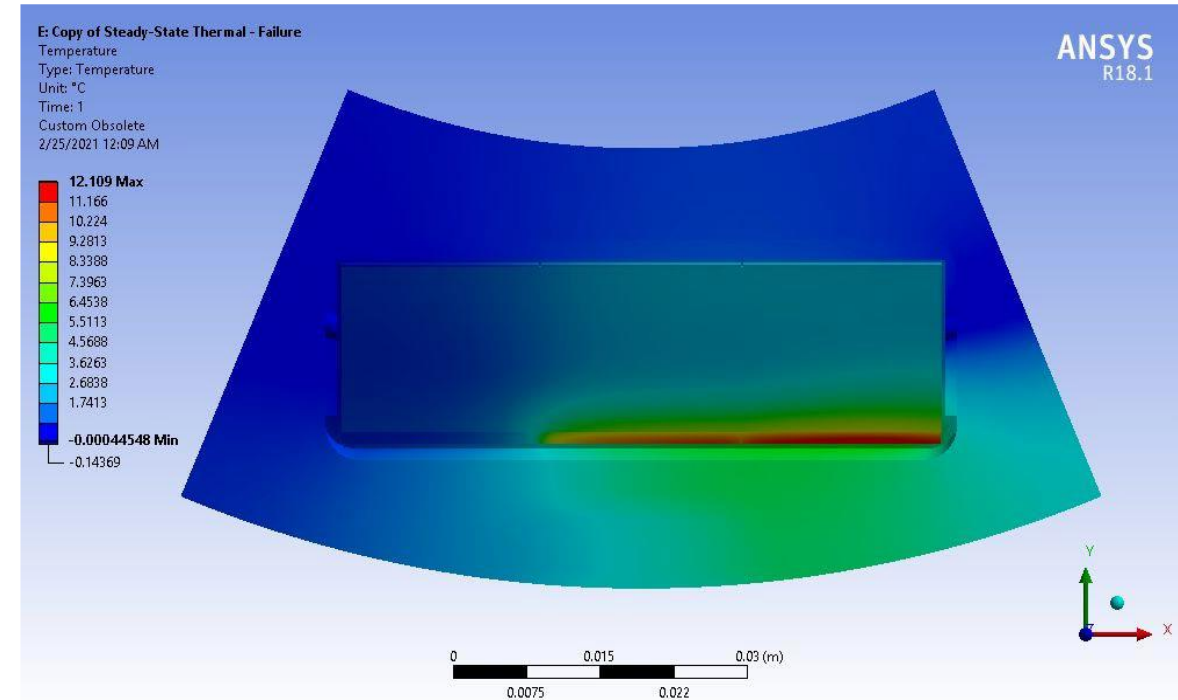


Cooling simulations

Reproduced from
Pixel Luminosity Ring
Project Description



Initial FEA thermal simulation of the PLR ring with a linear triplet module - the mechanical structure used in the calculation is the same as shown in the previous two figures. The geometry and heat-flow impedances should be fairly accurately modelled. This figure is for a "normal operation" scenario for the Shunt-LDOs. The $\Delta T \approx 5^\circ$ is well within requirements



Initial FEA thermal simulation of the PLR ring with a linear triplet module - the mechanical structure used in the calculation is the same as shown in the previous two figures. The geometry and heat-flow impedances should be fairly accurately modelled. This figure is for a "one-ASIC-open failure mode" scenario for the Shunt-LDOs, where the current that would normally power the leftmost ASIC is diverted through the other two ASICs, leading to additional heating. The $\Delta T \approx 12^\circ$ is quite reasonable.

- Task 1: prepare for the MoU and pre-production review (TDAQ or the number of data-links, mechanical stability, the module loading accuracy....)
- Task 2: complete the CAD design
 - Flex cable design
 - Power line design
- Task 3: organize for integration in to ITk.

WP 1: production of 230 sensors by Genoa. (2x8x3x4x1.2)

WP 2: hybridization of 230 sensors. (ATLAS ?) extension of inner tracker upgrade.

WP 3: 16 straight ring triplets production. Norway.

WP 3.1.1: production of 16 (20?) printed circuits

WP 3.1.2: SMD loading

WP 3.1.3: Visual inspection

WP 3.2.1: assemble flex with modules

WP 3.2.2: Extended test package

WP 3.2.3: mounting of modules on wedges?

WP 4: production of 4 “ring 0 – type” patch panels. (US ?).

WP 4.1: design of local support (check compatibility with patch panels: 2 patch panels per local support)

WP 4.2: production of local support including wedges

WP 5: production of 2 local support rings with embedded cooling pipes and 16 wedges (US ?)

WP 6: cooling. Thermal budget estimate. Cooling test. Cooling lines at CERN (fit into the inner tracker). (Itk Danilo Giugni, Erik Vigeolas)

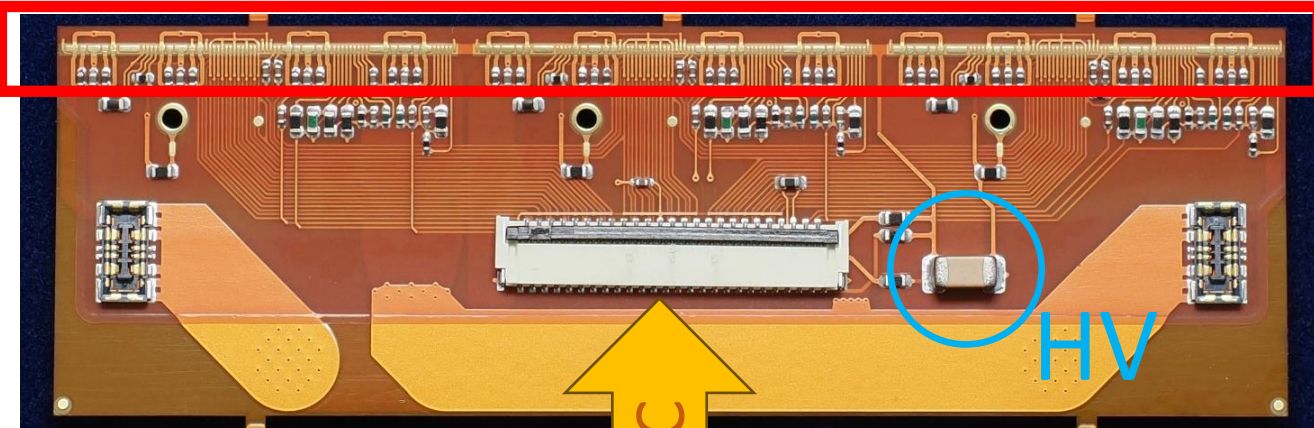
WP 7: loading on inner tracker (US ?).

WP 8: loading of inner tracker at CERN.

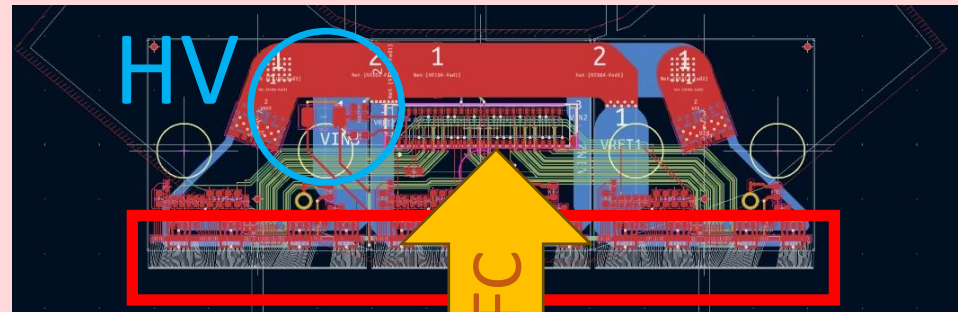
Bond row

UiO flex design solution

Linear triplet (starting point):
connector in the "wrong" direction

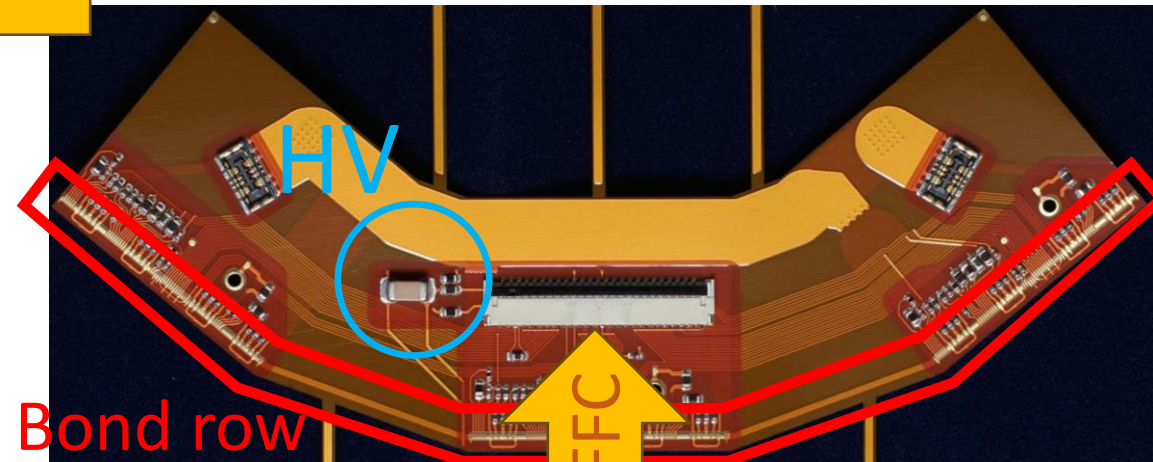


Straight ring triplet
pin connector in the "right" direction



Bond row

Ring 0 triplet:
connector in the "right" direction



Bond row



